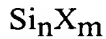


14. (Twice Amended) An ink-jet ink composition for forming a silicon film, comprising:

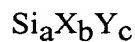
a silicon compound represented



B3 concl
n representing an integer 3 or more, m representing an integer of n, 2n-2, 2n, or 2n+2, and X representing a hydrogen atom and/or a halogen atom, the silicon compound having at least one cyclic structure.

15. (Twice Amended) An ink-jet ink composition for forming a silicon film, comprising:

a silicon compound represented by



X representing a hydrogen atom and/or a halogen atom, Y representing a boron atom or a phosphorus atom, a representing an integer of 3 or more, b representing an integer of a to 2a+c+2, and c representing an integer of 1 to a, the silicon compound having at least one cyclic structure.

B4
22. (Twice Amended) The ink composition according to claim 14, the composition having a viscosity of 1 to 50 mPa·s and a surface tension of 20 to 70 dyn/cm.

B5
[Please add new claim 23 as follows:]

--23. A method for forming a silicon film, comprising:

applying by patterning an ink composition containing a silicon compound onto a substrate by an ink jet process, the silicon compound is a composition containing a silicon compound represented by the following general formula and a silicon compound represented by

